

MATERIAL DATA SHEET

Material #	CDBQR series (0402) (Halogen Free)	
Product Line	SOD-923F	
Date	2012/3/26	
Rev.	H	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	FR-4 Board	Substrate/ Terminal	0.223	Copper	7440-50-8	43.00%	29.0%	
				Nickel	7440-02-0	3.677%		
				Gold	7440-57-5	0.099%		
				Continuous Filament Fiber Glass	65997-17-3	53.22%		
2	Wafer	Diode	0.029	Silicon	7440-21-3	92.00%	3.8%	
				Aluminum	7429-90-5	1.30%		
				Titanium	7440-32-6	0.20%		
				Gold	7440-57-5	6.50%		
3	Al wire	Conductor	0.001	Aluminum	7429-90-5	99.00%	0.1%	
				Silicon	7440-21-3	1.00%		
4	Silver paste	Welding	0.005	Modified Epoxy Resin	29690-82-2	5~25%	0.7%	
				Silver	7440-22-4	76~85%		
				Imidazole	827-43-0	1~4%		
				Amide	461-58-5	1~4%		
5	Molding Compound	Outer	0.511	Silica	60676-86-0	70~90%	66.4%	
				Epoxy Resin	29690-82-2	6~16%		
				Phenolic Resin	9003-35-4	5~15%		
				Carbon Black	1333-86-4	0.1~1%		
Total weight			0.769					